FINAL COM'L: -15/20 IND: -18/24

# MACH130-15/20

## **Lattice Semiconductor**

# **High-Density EE CMOS Programmable Logic**

## DISTINCTIVE CHARACTERISTICS

- 84 Pins
- 64 Macrocells
- 15 ns t<sub>PD</sub> Commercial
   18 ns t<sub>PD</sub> Industrial
- 66.6 MHz f<sub>CNT</sub>
- 70 Inputs

- 64 Outputs
- 64 Flip-flops; 4 clock choices
- 4 "PAL26V16" Blocks
- Pin-compatible with MACH131, MACH230, MACH231, MACH435

## **GENERAL DESCRIPTION**

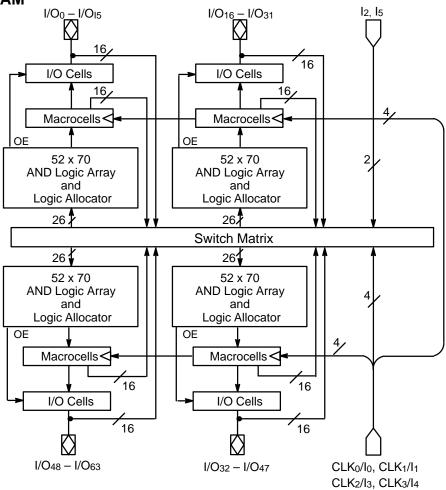
The MACH130 is a member of the high-performance EE CMOS MACH 1 family. This device has approximately six times the logic macrocell capability of the popular PAL22V10 without loss of speed.

The MACH130 consists of four PAL blocks interconnected by a programmable switch matrix. The switch matrix connects the PAL blocks to each other and to all input pins, providing a high degree of connectivity between the fully-connected PAL blocks. This allows designs to be placed and routed efficiently.

The MACH130 macrocell provides either registered or combinatorial outputs with programmable polarity. If a registered configuration is chosen, the register can be configured as D-type or T-type to help reduce the number of product terms. The register type decision can be made by the designer or by the software. All macrocells can be connected to an I/O cell. If a buried macrocell is desired, the internal feedback path from the macrocell can be used, which frees up the I/O pin for use as an input.

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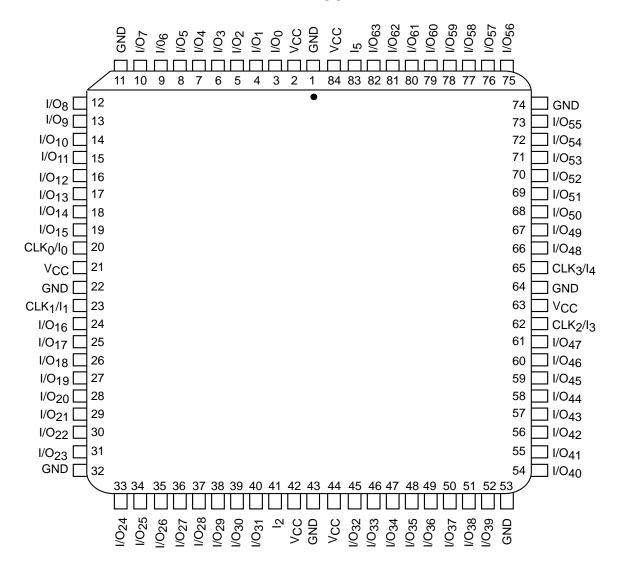
## **BLOCK DIAGRAM**



14131H-1

# CONNECTION DIAGRAM Top View





Note: Pin-compatible with MACH131, MACH230, MACH231, and MACH435.

14131H-2

## **PIN DESIGNATIONS**

CLK/I = Clock or Input

GND = Ground

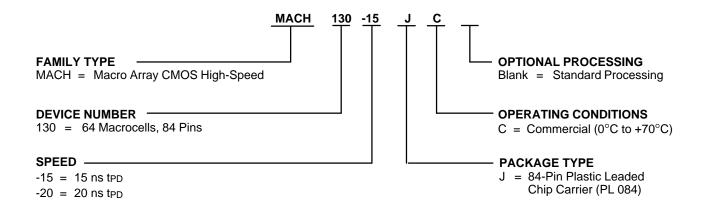
I = Input

I/O = Input/Output

Vcc = Supply Voltage

# ORDERING INFORMATION Commercial Products

Programmable logic products for commercial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



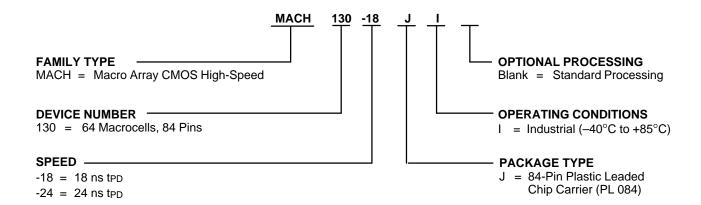
Valid Combinations						
MACH130-15	10					
MACH130-20	JC					

## **Valid Combinations**

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult your local sales office to confirm availability of specific valid combinations and to check on newly released combinations.

# ORDERING INFORMATION Industrial Products

Programmable logic products for industrial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



Valid Combinations					
MACH130-18					
MACH130-24	JI				

## **Valid Combinations**

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult your local sales office to confirm availability of specific valid combinations and to check on newly released combinations.

## **FUNCTIONAL DESCRIPTION**

The MACH130 consists of four PAL blocks connected by a switch matrix. There are 64 I/O pins and 2 dedicated input pins feeding the switch matrix. These signals are distributed to the four PAL blocks for efficient design implementation. There are 4 clock pins that can also be used as dedicated inputs.

### The PAL Blocks

Each PAL block in the MACH130 (Figure 1) contains a 64-product-term logic array, a logic allocator, 16 macrocells and 16 I/O cells. The switch matrix feeds each PAL block with 26 inputs. This makes the PAL block look effectively like an independent "PAL26V16".

There are four additional output enable product terms in each PAL block. For purposes of output enable, the 16 I/O cells are divided into 2 banks of 8 macrocells. Each bank is allocated two of the output enable product terms.

An asynchronous reset product term and an asynchronous preset product term are provided for flip-flop initialization. All flip-flops within the PAL block are initialized together.

## The Switch Matrix

The MACH130 switch matrix is fed by the inputs and feedback signals from the PAL blocks. Each PAL block provides 16 internal feedback signals and 16 I/O feedback signals. The switch matrix distributes these signals back to the PAL blocks in an efficient manner that also provides for high performance. The design software automatically configures the switch matrix when fitting a design into the device.

## The Product-Term Array

The MACH130 product-term array consists of 64 product terms for logic use, and 6 special-purpose product terms. Four of the special-purpose product terms provide programmable output enable, one provides asynchronous reset, and one provides asynchronous preset. Two of the output enable product terms are used for the first eight I/O cells; the other two control the last eight macrocells.

## The Logic Allocator

The logic allocator in the MACH130 takes the 64 logic product terms and allocates them to the 16 macrocells as needed. Each macrocell can be driven by up to 12 product terms. The design software automatically configures the logic allocator when fitting the design into the device.

Table 1 illustrates which product term clusters are available to each macrocell within a PAL block. Refer to Figure 1 for cluster and macrocell numbers.

**Table 1. Logic Allocation** 

	I
	Available
Output Macrocell	Clusters
M <sub>0</sub>	C <sub>0</sub> , C <sub>1</sub>
M <sub>1</sub>	C <sub>0</sub> , C <sub>1</sub> , C <sub>2</sub>
M <sub>2</sub>	C <sub>1</sub> , C <sub>2</sub> , C <sub>3</sub>
M <sub>3</sub>	C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub>
M <sub>4</sub>	C <sub>3</sub> , C <sub>4</sub> , C <sub>5</sub>
M <sub>5</sub>	C <sub>4</sub> , C <sub>5</sub> , C <sub>6</sub>
M <sub>6</sub>	C <sub>5</sub> , C <sub>6</sub> , C <sub>7</sub>
M <sub>7</sub>	C <sub>6</sub> , C <sub>7</sub> , C <sub>8</sub>
M <sub>8</sub>	C <sub>7</sub> , C <sub>8</sub> , C <sub>9</sub>
M <sub>9</sub>	C <sub>8</sub> , C <sub>9</sub> , C <sub>10</sub>
M <sub>10</sub>	C <sub>9</sub> , C <sub>10</sub> , C <sub>11</sub>
M <sub>11</sub>	C <sub>10</sub> , C <sub>11</sub> , C <sub>12</sub>
M <sub>12</sub>	C <sub>11</sub> , C <sub>12</sub> , C <sub>13</sub>
M <sub>13</sub>	C <sub>12</sub> , C <sub>13</sub> , C <sub>14</sub>
M <sub>14</sub>	C13, C14, C15
M <sub>15</sub>	C <sub>14</sub> , C <sub>15</sub>

## The Macrocell

The MACH130 macrocells can be configured as either registered or combinatorial, with programmable polarity. The macrocell provides internal feedback whether configured as registered or combinatorial. The flip-flops can be configured as D-type or T-type, allowing for product-term optimization.

The flip-flops can individually select one of four global clock pins, which are also available as logic inputs. The registers are clocked on the LOW-to-HIGH transition of the clock signal. The flip-flops can also be asynchronously initialized with the common asynchronous reset and preset product terms.

## The I/O Cell

The I/O cell in the MACH130 consists of a three-state output buffer. The three-state buffer can be configured in one of three ways: always enabled, always disabled, or controlled by a product term. If product term control is chosen, one of two product terms may be used to provide the control. The two product terms that are available are common to eight I/O cells. Within each PAL block, two product terms are available for selection by the first eight three-state outputs; two other product terms are available for selection by the last eight three-state outputs.

These choices make it possible to use the macrocell as an output, an input, a bidirectional pin, or a three-state output for use in driving a bus.

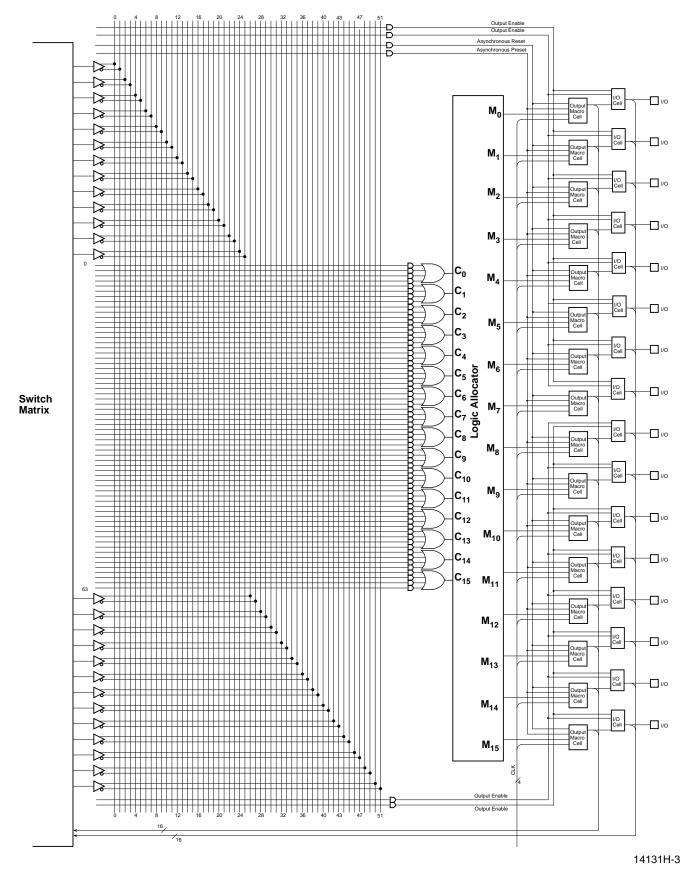


Figure 1. MACH130 PAL Block

## **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature65°C to +150°C
Ambient Temperature With Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage $-0.5$ V to V <sub>CC</sub> + $0.5$ V
DC Output or I/O
Pin Voltage $\dots -0.5 \text{ V}$ to $V_{CC} + 0.5 \text{ V}$
Static Discharge Voltage 2001 V
Latchup Current
$(T_A = 0^{\circ}C \text{ to } 70^{\circ}C) \dots 200 \text{ mA}$

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

## **OPERATING RANGES**

## **Commercial (C) Devices**

Ambient Temperature (T<sub>A</sub>)
Operating in Free Air . . . . . 0°C to +70°C
Supply Voltage (V<sub>CC</sub>)
with Respect to Ground . . . . +4.75 V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

## DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Voн	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = Min$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	٧
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V <sub>IL</sub>	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I <sub>IH</sub>	Input HIGH Current	V <sub>IN</sub> = 5.25 V, V <sub>CC</sub> = Max (Note 2)			10	μΑ
I⊫	Input LOW Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)			-10	μΑ
I <sub>OZH</sub>	Off-State Output Leakage Current HIGH	$V_{OUT}$ = 5.25 V, $V_{CC}$ = Max $V_{IN}$ = $V_{IH}$ or $V_{IL}$ (Note 2)			10	μΑ
lozL	Off-State Output Leakage Current LOW	V <sub>OUT</sub> = 0 V, V <sub>CC</sub> = Max V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> (Note 2)			-10	μΑ
Isc	Output Short-Circuit Current	V <sub>OUT</sub> = 0.5 V, V <sub>CC</sub> = Max (Note 3)	-30		-130	mA
Icc	Supply Current (Typical)	$V_{CC} = 5V$ , $T_A = 25$ °C, $f = 25$ MHz (Note 4)		190		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

## **CAPACITANCE (Note 1)**

Parameter Symbol	Parameter Description	Test Conditi	ons	Тур	Unit
Cin	Input Capacitance	V <sub>IN</sub> = 2.0 V	Vcc = 5.0 V, T <sub>A</sub> = 25°C	6	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

# **SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)**

Parameter						5	-20		
Symbol	Parameter De	escription			Min	Max	Min	Max	Unit
t <sub>PD</sub>		nput, I/O, or Feedback to Combinatorial Dutput (Note 3)				15		20	ns
ts			D-type	10		13		ns	
เร	to Clock			T-type	11		14		ns
tн	Hold Time			•	0		0		ns
tco	Clock to Outpo	ut (Note 3)				10		12	ns
t <sub>WL</sub>	Clock Width			LOW	6		8		ns
t <sub>WH</sub>				HIGH	6		8		ns
	Maximum - Frequency	External Feedback	D-type	D-type	50		40		MHz
			k 1/(ts + tco)	T-type	47.6		38.5		MHz
$f_{MAX}$		D-type		66.6		47.6		MHz	
		Internal Feedback	(fCNT)	T-type	55.5		43.5		MHz
		No Feedback	1/(twL + twH)	•	83.3		62.5		MHz
tar	Asynchronous	Reset to Registered	d Output			20		25	ns
t <sub>ARW</sub>	Asynchronous	Reset Width (Note	1)		15		20		ns
t <sub>ARR</sub>	Asynchronous	Reset Recovery Tir	me (Note 1)		10		15		ns
t <sub>AP</sub>	Asynchronous	Preset to Registere	d Output			20		25	ns
tapw	Asynchronous Preset Width (Note 1)		15		20		ns		
tapr	Asynchronous Preset Recovery Time (Note 1)			10		15		ns	
t <sub>EA</sub>	Input, I/O, or F	Input, I/O, or Feedback to Output Enable (Note 3)				15		20	ns
t <sub>ER</sub>	Input, I/O, or F	eedback to Output I	Disable (Note 3)			15		20	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 32 outputs switching.

## **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature $$ $-65^{\circ}$ C to $+150^{\circ}$ C
Ambient Temperature With Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage –0.5 V to V <sub>CC</sub> + 0.5 V
DC Output or I/O
Pin Voltage $-0.5$ V to $V_{CC}$ + $0.5$ V
Static Discharge Voltage 2001 V
Latchup Current $ (T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}) \ \dots \ 200 \text{ mA} $

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

## **INDUSTRIAL OPERATING RANGES**

Ambient Temperature ( $T_A$ )
Operating in Free Air ..... -40°C to +85°C
Supply Voltage ( $V_{CC}$ )
with Respect to Ground ..... +4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

## DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	$I_{OH}$ = -3.2 mA, $V_{CC}$ = Min $V_{IN}$ = $V_{IH}$ or $V_{IL}$	2.4			٧
VoL	Output LOW Voltage	$I_{OL}$ = 16 mA, $V_{CC}$ = Min $V_{IN}$ = $V_{IH}$ or $V_{IL}$			0.5	V
V <sub>IH</sub>	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I <sub>IH</sub>	Input HIGH Current	V <sub>IN</sub> = 5.25 V, V <sub>CC</sub> = Max (Note 2)			10	μΑ
IιL	Input LOW Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)			-10	μΑ
lozh	Off-State Output Leakage Current HIGH	V <sub>OUT</sub> = 5.25 V, V <sub>CC</sub> = Max V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> (Note 2)			10	μΑ
lozL	Off-State Output Leakage Current LOW	V <sub>OUT</sub> = 0 V, V <sub>CC</sub> = Max V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> (Note 2)			-10	μΑ
I <sub>SC</sub>	Output Short-Circuit Current	V <sub>OUT</sub> = 0.5 V, V <sub>CC</sub> = Max (Note 3)	-30		-130	mA
Icc	Supply Current (Typical)	$V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}, f = 25 \text{ MHz (Note 4)}$		190		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I<sub>IL</sub> and I<sub>OZL</sub> (or I<sub>IH</sub> and I<sub>OZH</sub>).
- 3. Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

## **CAPACITANCE (Note 1)**

Parameter Symbol	Parameter Description	Test Conditi	ons	Тур	Unit
C <sub>IN</sub>	Input Capacitance	$V_{IN} = 2.0 \text{ V}$	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C}$	6	pF
Соит	Output Capacitance	V <sub>OUT</sub> = 2.0 V	f = 1 MHz	8	pF

# **SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)**

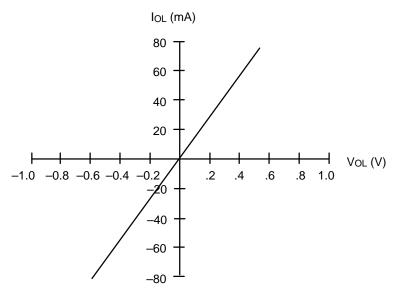
Parameter				-1	8	-24			
Symbol	Parameter De	scription			Min	Max	Min	Max	Unit
t <sub>PD</sub>	Input, I/O, or Feedback to Combinatorial Output (Note 3)			18		24	ns		
	Setup Time from Input, I/O, or Feedback  D-type		12		16		ns		
ts	to Clock	, , ,		T-type	13.5		17		ns
t <sub>H</sub>	Hold Time			•	0		0		ns
tco	Clock to Outpu	it (Note 3)				12		14.5	ns
t <sub>WL</sub>	Olerale Minister	LOW		7.5		10		ns	
twH	Clock Width			HIGH	7.5		10		ns
			External Feedback 1/(ts + tco) D-type	40		32		MHz	
	Maximum		17(13 1 100)	T-type	38		30		MHz
f <sub>MAX</sub>	Frequency	Internal Feedback (f <sub>CNT</sub> )		53		38		MHz	
	(Note 1)	ote 1)	(ICNI)	T-type	44		34.5		MHz
		No Feedback	1/(t <sub>WL</sub> + t <sub>WH</sub> )		66.5		50		MHz
t <sub>AR</sub>	Asynchronous	Reset to Registered	Output			24		30	ns
t <sub>ARW</sub>	Asynchronous	Reset Width (Note 1)	)		18		24		ns
t <sub>ARR</sub>	Asynchronous	Reset Recovery Time	e (Note 1)		12		18		ns
t <sub>AP</sub>	Asynchronous Preset to Registered Output			24		30	ns		
t <sub>APW</sub>	Asynchronous Preset Width (Note 1)		18		24		ns		
t <sub>APR</sub>	Asynchronous Preset Recovery Time (Note 1)		12		18		ns		
$t_{\sf EA}$	Input, I/O, or F	eedback to Output Er	nable (Note 3)			18		24	ns
t <sub>ER</sub>	Input, I/O, or F	eedback to Output Di	isable (Note 3)			18		24	ns

<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

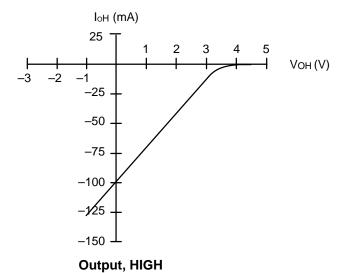
<sup>2.</sup> See Switching Test Circuit, for test conditions.

<sup>3.</sup> Parameters measured with 32 outputs switching.

# TYPICAL CURRENT VS. VOLTAGE (I-V) CHARACTERISTICS $V_{CC} = 5.0 \ V, \ T_A = 25^{\circ}C$

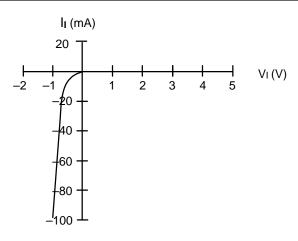


**Output, LOW** 



14131H-5

14131H-4

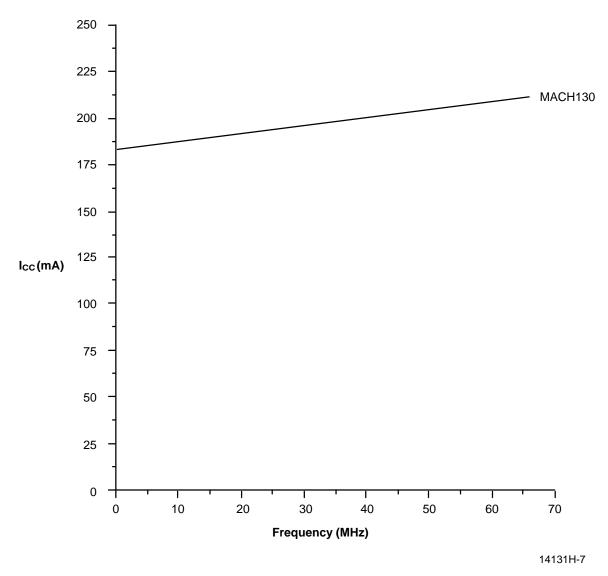


14131H-6

Input

12

# TYPICAL $I_{CC}$ CHARACTERISTICS $V_{CC} = 5$ V, $T_A = 25$ °C



The selected "typical" pattern is a 16-bit up/down counter. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

Maximum frequency shown uses internal feedback and a D-type register.

## TYPICAL THERMAL CHARACTERISTICS

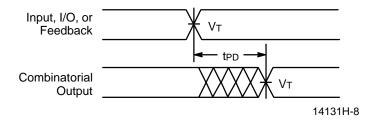
Measured at 25°C ambient. These parameters are not tested.

Parameter			Тур	
Symbol	Parameter Description		PLCC	Unit
θјс	Thermal impedance, junction to case	13	°C/W	
$\theta_{ja}$	Thermal impedance, junction to ambient	34	°C/W	
θjma	θ <sub>jma</sub> Thermal impedance, junction to		30	°C/W
	ambient with air flow	400 lfpm air	28	°C/W
		600 Ifpm air	26	°C/W
		800 lfpm air	25	°C/W

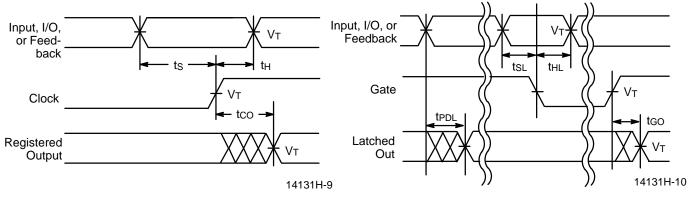
## Plastic θ jc Considerations

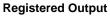
The data listed for plastic  $\theta$ jc are for reference only and are not recommended for use in calculating junction temperatures. The heat-flow paths in plastic-encapsulated devices are complex, making the  $\theta$ jc measurement relative to a specific location on the package surface. Tests indicate this measurement reference point is directly below the die-attach area on the bottom center of the package. Furthermore,  $\theta$ jc tests on packages are performed in a constant-temperature bath, keeping the package surface at a constant temperature. Therefore, the measurements can only be used in a similar environment.

## **SWITCHING WAVEFORMS**

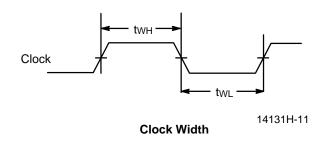


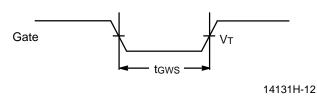
## **Combinatorial Output**



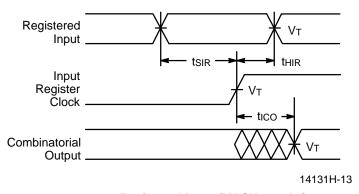


Latched Output (MACH 2, 3, and 4)

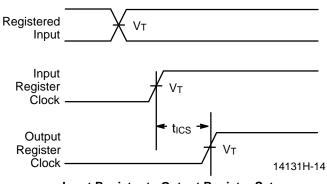




Gate Width (MACH 2, 3, and 4)



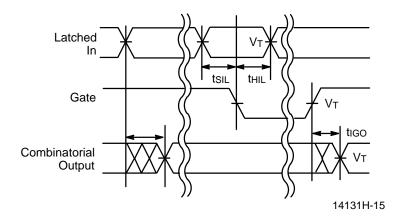
Registered Input (MACH 2 and 4)



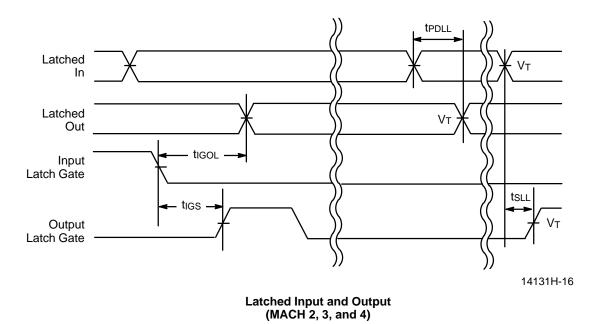
Input Register to Output Register Setup (MACH 2 and 4)

- 1. VT = 1.5 V.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

## **SWITCHING WAVEFORMS**



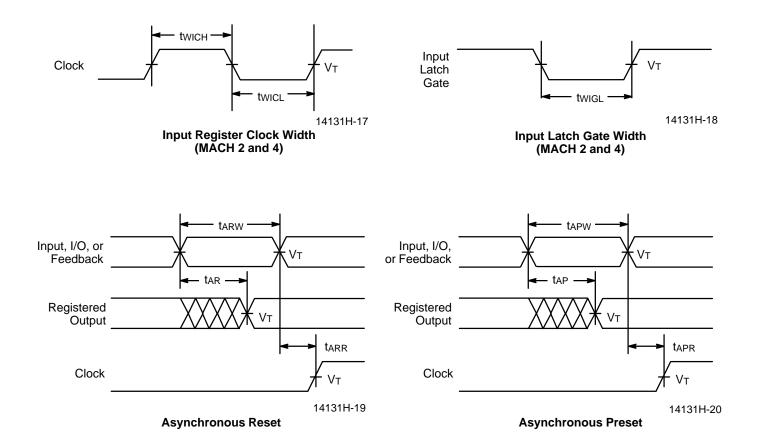
Latched Input (MACH 2 and 4)

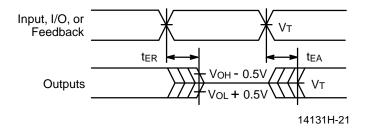


Notes:

- 1. VT = 1.5 V.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

## **SWITCHING WAVEFORMS**

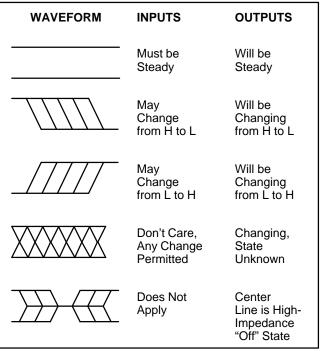




**Output Disable/Enable** 

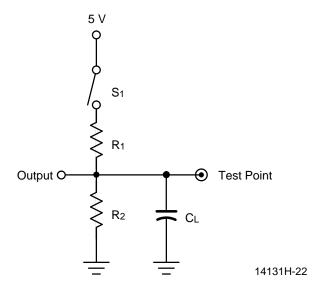
- 1.  $V_T = 1.5 V$ .
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

## **KEY TO SWITCHING WAVEFORMS**



KS000010-PAL

## **SWITCHING TEST CIRCUIT**



			Commercial		Measured
Specification	S <sub>1</sub>	C∟	R <sub>1</sub>	<b>R</b> <sub>2</sub>	Output Value
tpd, tco	Closed				1.5 V
t <sub>EA</sub>	$Z \rightarrow H$ : Open $Z \rightarrow L$ : Closed	35 pF	300 Ω	390 Ω	1.5 V
ter	$H \rightarrow Z$ : Open $L \rightarrow Z$ : Closed	5 pF			$H \rightarrow Z: V_{OH} - 0.5 V$ $L \rightarrow Z: V_{OL} + 0.5 V$

<sup>\*</sup>Switching several outputs simultaneously should be avoided for accurate measurement.

## **fMAX PARAMETERS**

The parameter f<sub>MAX</sub> is the maximum clock rate at which the device is guaranteed to operate. Because the flexibility inherent in programmable logic devices offers a choice of clocked flip-flop designs, f<sub>MAX</sub> is specified for three types of synchronous designs.

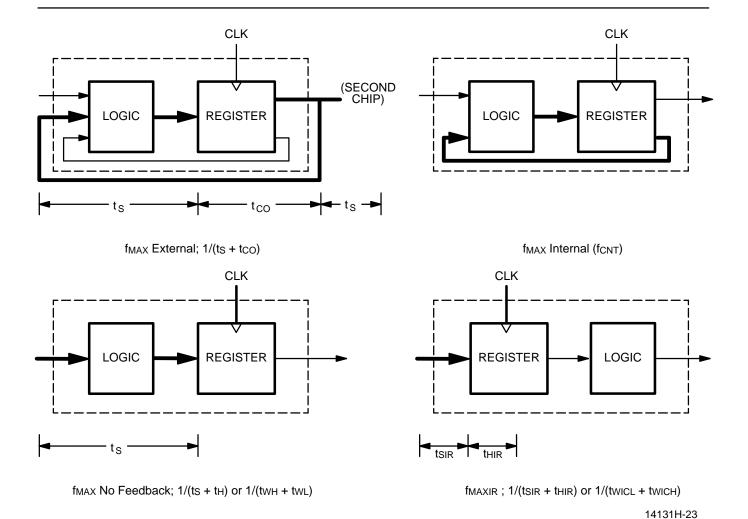
The first type of design is a state machine with feedback signals sent off-chip. This external feedback could go back to the device inputs, or to a second device in a multi-chip state machine. The slowest path defining the period is the sum of the clock-to-output time and the input setup time for the external signals ( $t_S + t_{CO}$ ). The reciprocal,  $f_{MAX}$ , is the maximum frequency with external feedback or in conjunction with an equivalent speed device. This  $f_{MAX}$  is designated " $f_{MAX}$  external."

The second type of design is a single-chip state machine with internal feedback only. In this case, flip-flop inputs are defined by the device inputs and flip-flop outputs. Under these conditions, the period is limited by the internal delay from the flip-flop outputs through the internal feedback and logic to the flip-flop inputs. This  $f_{\text{MAX}}$  is designated " $f_{\text{MAX}}$  internal". A simple internal counter is a good example of this type of design; therefore, this parameter is sometimes called " $f_{\text{CNT}}$ ."

The third type of design is a simple data path application. In this case, input data is presented to the flip-flop and clocked through; no feedback is employed. Under these conditions, the period is limited by the sum of the data setup time and the data hold time ( $t_S + t_H$ ). However, a lower limit for the period of each  $f_{MAX}$  type is the minimum clock period ( $t_{WH} + t_{WL}$ ). Usually, this minimum clock period determines the period for the third  $f_{MAX}$ , designated " $f_{MAX}$  no feedback."

For devices with input registers, one additional  $f_{MAX}$  parameter is specified:  $f_{MAXIR}$ . Because this involves no feedback, it is calculated the same way as  $f_{MAX}$  no feedback. The minimum period will be limited either by the sum of the setup and hold times ( $t_{SIR} + t_{HIR}$ ) or the sum of the clock widths ( $t_{WICL} + t_{WICH}$ ). The clock widths are normally the limiting parameters, so that  $f_{MAXIR}$  is specified as  $1/(t_{WICL} + t_{WICH})$ . Note that if both input and output registers are use in the same path, the overall frequency will be limited by  $t_{ICS}$ .

All frequencies except  $f_{\text{MAX}}$  internal are calculated from other measured AC parameters.  $f_{\text{MAX}}$  internal is measured directly.



## **ENDURANCE CHARACTERISTICS**

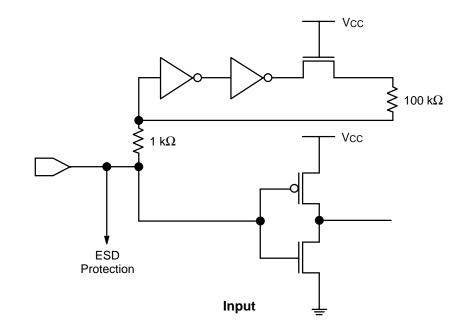
The MACH families are manufactured using our advanced Electrically Erasable process. This technology uses an EE cell to replace the fuse link used in

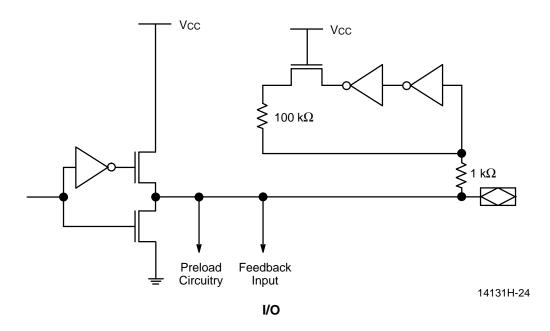
bipolar parts. As a result, the device can be erased and reprogrammed, a feature which allows 100% testing at the factory.

## **Endurance Characteristics**

Parameter Symbol	Parameter Description	Min	Units	Test Conditions
		10	Years	Max Storage Temperature
t <sub>DR</sub>	Min Pattern Data Retention Time	20	Years	Max Operating Temperature
N	Max Reprogramming Cycles	100	Cycles	Normal Programming Conditions

## INPUT/OUTPUT EQUIVALENT SCHEMATICS





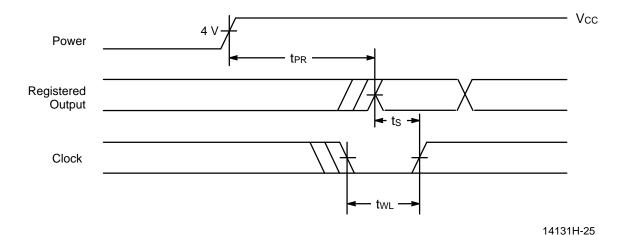
## **POWER-UP RESET**

The MACH devices have been designed with the capability to reset during system power-up. Following power-up, all flip-flops will be reset to LOW. The output state will depend on the logic polarity. This feature provides extra flexibility to the designer and is especially valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below. Due to the synchronous operation of the power-up reset and the

wide range of ways  $V_{\text{CC}}$  can rise to its steady state, two conditions are required to insure a valid power-up reset. These conditions are:

- 1. The Vcc rise must be monotonic.
- 2. Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Descriptions	Max	Unit	
t <sub>PR</sub>	Power-Up Reset Time	10	μs	
ts	Input or Feedback Setup Time	See		
twL	Clock Width LOW	Characteris	- Switching Characteristics	



**Power-Up Reset Waveform** 

## **USING PRELOAD AND OBSERVABILITY**

In order to be testable, a circuit must be both controllable and observable. To achieve this, the MACH devices incorporate register preload and observability.

In preload mode, each flip-flop in the MACH device can be loaded from the I/O pins, in order to perform functional testing of complex state machines. Register preload makes it possible to run a series of tests from a known starting state, or to load illegal states and test for proper recovery. This ability to control the MACH device's internal state can shorten test sequences, since it is easier to reach the state of interest.

The observability function makes it possible to see the internal state of the buried registers during test by overriding each register's output enable and activating the output buffer. The values stored in output and buried registers can then be observed on the I/O pins. Without this feature, a thorough functional test would be impossible for any designs with buried registers.

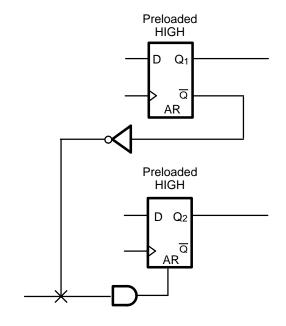
While the implementation of the testability features is fairly straightforward, care must be taken in certain instances to insure valid testing.

One case involves asynchronous reset and preset. If the MACH registers drive asynchronous reset or preset lines and are preloaded in such a way that reset or preset are asserted, the reset or preset may remove the preloaded data. This is illustrated in Figure 2. Care should be taken when planning functional tests, so that states that will cause unexpected resets and presets are not preloaded.

Another case to be aware of arises in testing combinatorial logic. When an output is configured as combinatorial, the observability feature forces the output into registered mode. When this happens, all product terms are forced to zero, which eliminates all combinatorial data. For a straight combinatorial output, the correct value will be restored after the preload or observe function, and there will be no problem. If the function implements a combinatorial latch, however, it relies on feedback to hold the correct value, as shown in Figure 3. As this value may change during the preload or observe operation, you cannot count on the data being correct after the operation. To insure valid testing in these cases, outputs that are combinatorial latches should not be tested immediately following a preload or observe sequence, but should first be restored to a known state.

All MACH 2 devices support both preload and observability.

Contact individual programming vendors in order to verify programmer support.



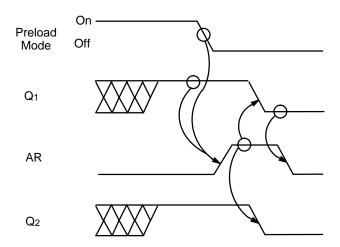


Figure 2. Preload/Reset Conflict

14131H-26

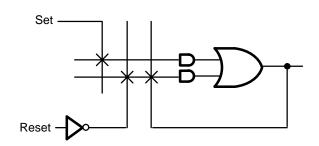


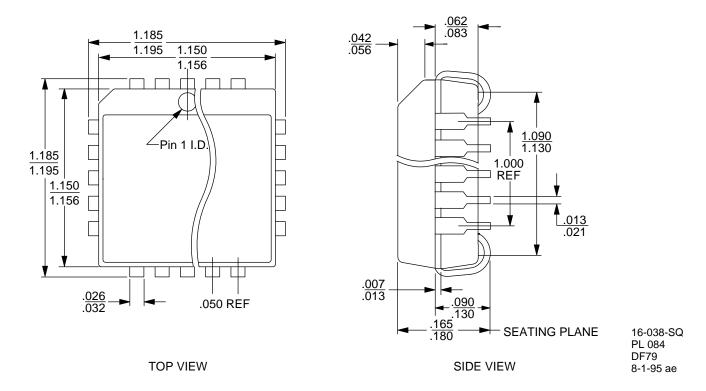
Figure 3. Combinatorial Latch

14131H-27

## **PHYSICAL DIMENSIONS\***

## PL 084

# 84-Pin Plastic Leaded Chip Carrier (measured in inches)



<sup>\*</sup>For reference only. BSC is an ANSI standard for Basic Space Centering.